



FEATURES

ESD protection for high speed data lines to IEC61	_000-4-2
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| ESD contact discharge typical 8KV, max 15KV

| ESD air discharge typical 15KV, max 25KV

Surface mount

| Extremely low capacitance

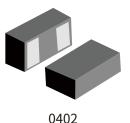
I Very low leakage current

Fast response time

| Bi-directional ESD protection

Lead free solder termination

The best ESD protection for high frequency, low voltage applications





Schematic Symbol

APPLICATIONS

ı	High Definition	Multi-Media	Interface (HDMI))

| Digital Visual Interface (DVI)

| Display Port Interface (DP)

| Unified Display Interface (UDI)

| Mobile Display Digital Interface (MDDI)

| Gigabit Ethernet

USB2.0 and USB3.0

IEEE1394 interface

APPROVALS

RoHS	Compliance with 2011/65/EU
HF	Compliance with IEC61249-2-21:2003

CAUTION

This component is designed for signal line protection only, Not intended to be used under bias, not for application with a power line.



ABSOLUTE MAXIMUM RATINGS

Symbol	Parameter	Value	Unit
-	Maximum Contact discharge voltage Per IEC61000-4-2	15KV	V
-	Maximum Air discharge voltage Per IEC61000-4-2	25KV	V
T _{OPER}	Maximum Operating temperature	-40 to +90	°C
T _{STG}	Maximum Storage temperature	-55 to +125	°C
T _L	Maximum lead temperature for soldering during 10s	260	°C

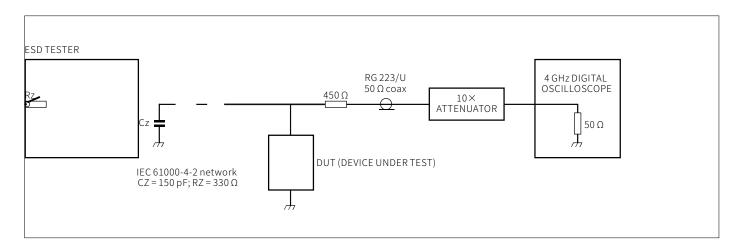
ELECTRICAL CHARACTERISTICS(T_A=25°C)

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
V_R	Rated Voltage	-	-	-	3.3	V
V _T	Trigger Voltage	IEC61000-4-28KV contact discharge	-	300	-	V
V _C	Clamping Voltage	IEC61000-4-28KV contact discharge	-	35	-	V
I	Leakage Current	DC 5V shall be applied on component	-	-	0.10	μΑ
C _P	Capacitance	$V_R = 0V, f = 1MHz$	-	0.05	-	pF

Note:

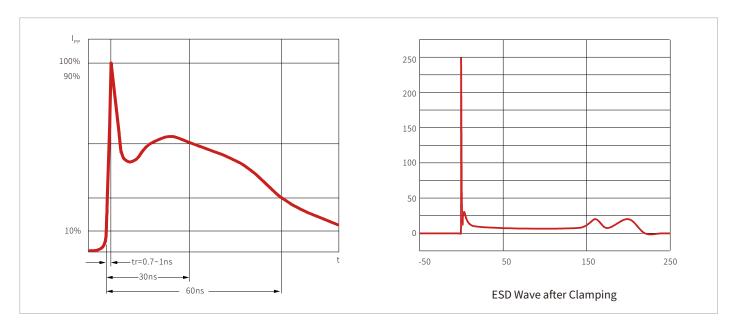
- 1, Trigger and clamping voltage are measured per IEC 61000-4-2, 8KV contact discharge method.
- $2. After \ reliability \ tests \ such as \ high \ temp \ storage, temp \ cycles, continuous \ ESD \ strike \ etc, the \ maximum \ leakage \ current \ is \ less \ than \ 10 uA.$

ESD CLAMPING TEST



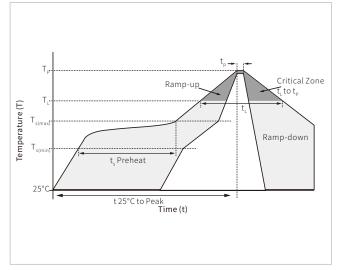


CHARACTERISTIC CURVES



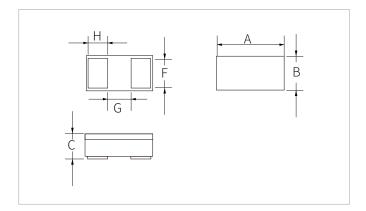
SOLDERING PARAMETERS

	Lead-free assembly		
	Temperature Max $(T_{s(min)})$	150°C	
Pre Heat	Temperature Max $(T_{s(max)})$	200°C	
	Time (min to max) (t_s)	60 – 180 secs	
Average ramp up rate (Liquidus Temp (T _L) to peak		3°C/second max	
	$T_{S(max)}$ to T_L - Ramp-up Rate	3°C/second max	
Reflow	Temperature (T _L) (Liquidus)	217°C	
Kellow	Time (min to max) (t_L)	60 – 150 seconds	
Peak Temp	Peak Temperature (T _P)		
Time within 5°C of actual peak Temperature (t _p)		20 – 40 seconds	
Ramp-dow	6°C/second max		
Time 25°C t	8 minutes max.		
Do not exce	260°C		



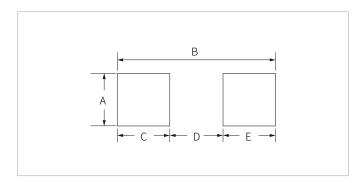


PACKAGE INFORMATION



Ref.	Dimension			
Kei.	Min. Typ Ma		Max.	Unit
А	0.95	1.0	1.05	
В	0.45	0.50	0.55	
С	0.32	0.36	0.40	
Н	0.28	0.30	0.32	mm
F	0.41	0.43	0.45	
G	0.32	0.34	0.36	

RECOMMENDED PAD LAYOUT DIMENSIONS



Ref.	Dimension	Unit
А	0.55	
В	1.05	
С	0.40	mm
D	0.25	
Е	0.40	

ORDERING INFORMATION

Part Number	Component Package	QTY/Reel	Reel Size
SAE0402B3.3UA	0402	10000PCS	7"



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